



SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	25.000000 MHz
PRODUCT TYPE	TYPE F9 5.0x3.2 GLASS SEALED CRYSTAL
SPEC. NO. (P/N)	F92500061Q
CUSTOMER P/N	
ISSUE DATE	August 10, 2018
VERSION	В

APPROVED	PREPARED	QA
Brenda	YINU	Dong Jang

Diodes Incorporated

No.2, Ziqiang 5th Rd., Zhongli Industrial Park, Zhongli Dist., Taoyuan City 32063, Taiwan (R.O.C.)

TEL: 886-3-451-8888 FAX: 886-3-461-3865 https://www.diodes.com

- *RoHS Exemption
- *HF-Halogen Free
- *REACH Compliant
- *AEC-Q200 Compliant

F92500061Q

VER. B 10-Aug-18

VERSION HISTORY

Verision Date	Description	Notes
Jan.11,2017	Initial Release	
Aug.10,2018	Updated logo	
	Date Jan.11,2017	Jan.11,2017 Initial Release



F92500061Q

VER. B 10-Aug-18

ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	25.000000	MHz	
Mode of Oscillation	МО	AT Cut-Fundamental		
Calibration Load Capacitance	CL	12	pF	
Calibration Tolerance	FL	±30	ppm	at 25℃±3℃
Operating Temperature Range	TR	-40 to +125	C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±120	ppm	Reference to the Frequency at 25℃
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	
Equivalent Series Resistance	ESR	40	Ω	Max
Shunt Capacitance	C0	5	pF	Max.
Aging at 25℃		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	C	
Insulation Resistance		500	МΩ	Min

F92500061Q

VER. B 10-Aug-18

AEC-Q200 RELIABILITY TEST SPECIFICATIONS:

1. Initial

1.1 Physical Dimensions: JESD22, Method JB1-100

1.2 External Visual: MIL-STD-883, Method 2009

1.3 Freq. Vs. Temperature: Per Specification/Datasheet

2. Mechanical

2.1 Mechanical Shock: MIL-STD-202 Method 213

2.2 Vibration: MIL-STD-202 Method 204

2.3 Solderability: J-STD-002

2.4 Board Flex: AEC Q200-005

2.5 Terminal Strength (SMD): AEC Q200-006

3.Environmental

3.1 Temp Cycle: JESD22, Method JA-104

3.2 Resistance to Solder Heat: MIL-STD-202 Method 210

3.3 High Temperature Operating Life: MIL-STD-202, Method 108

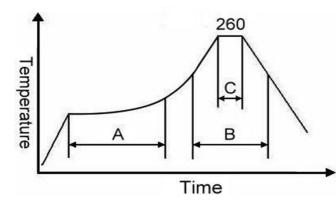
3.4 High Temp. Exposure: MIL-STD-202, Method 108

3.5 High Temp. & High Humidity: MIL-STD-202, Method 103

3.6 Thermal Shock: MIL-STD-202, Method 107

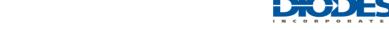
SUGGESTED IR REFLOW PROFILE

*As per IPC-JEDEC J-STD-020D



	1		
N	^1	-0	٠
1.4	v	יס	

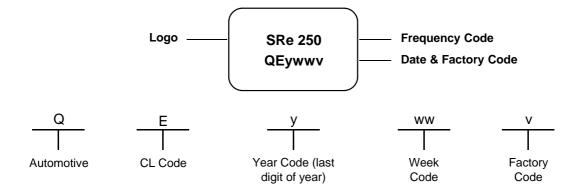
	Stage	Temperature	Time
Α	Preheat	150~200°C	60~120 Sec
В	Primary Heat	217°C	60~150 Sec
С	Peak	260°C	10 Sec



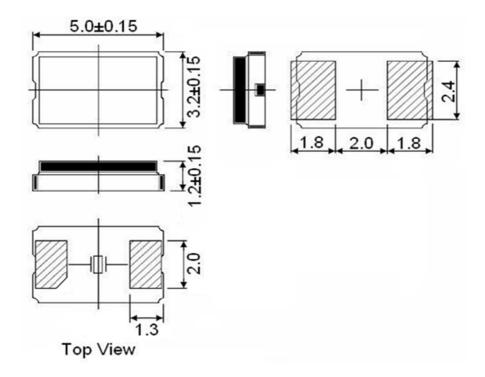
F92500061Q

VER. B 10-Aug-18

MARKING



MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)

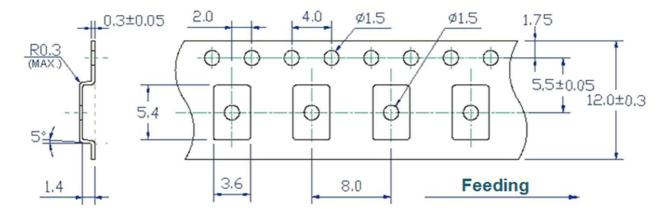


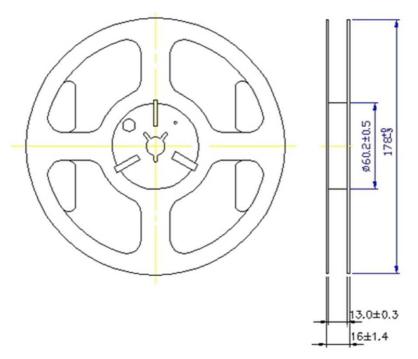
Note:

Pin shape is only for reference, and the Pin with chamfer or without chamfer is based on the real product.



Tape & Reel





- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

